

Electronic Patent Application Fee Transmittal

Application Number:	10008700			
Filing Date:	07-Dec-2001			
Title of Invention:	METHODS OF MANUFACTURING INTEGRATED CIRCUIT DEVICES HAVING AN ENCAPSULATED INSULATION LAYER			
First Named Inventor/Applicant Name:	Hong-Sik Jeong			
Filer:	David Moore/Candi Riggs			
Attorney Docket Number:	5649-905			
Filed as Large Entity				
Utility Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Utility Appt Issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Total in USD (\$)				1740